

Figure 1. Double Sided Copper Clad Laminate

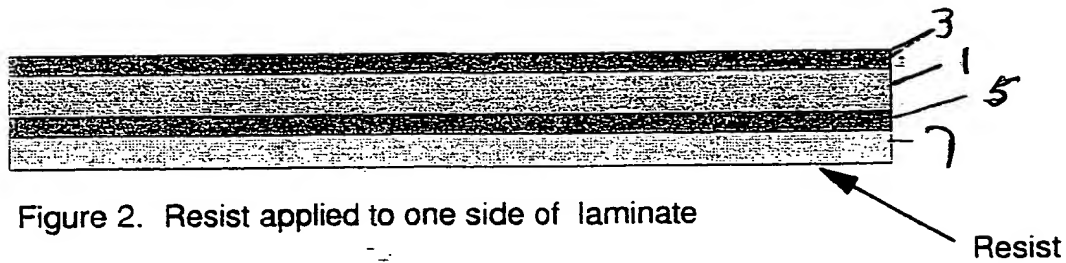


Figure 2. Resist applied to one side of laminate

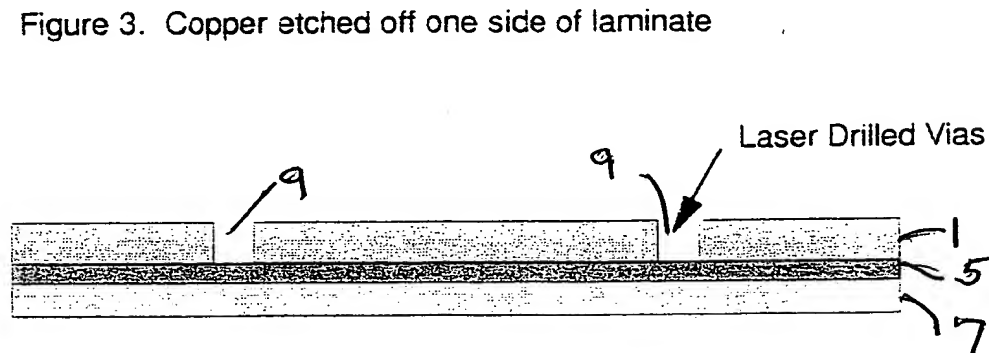
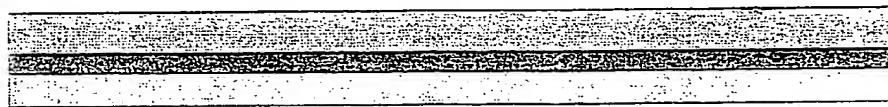


Figure 4. Via holes laser drilled

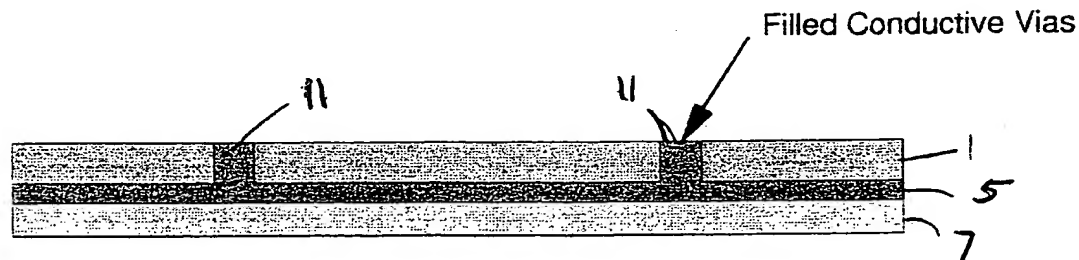


Figure 5. Via holes plated flush

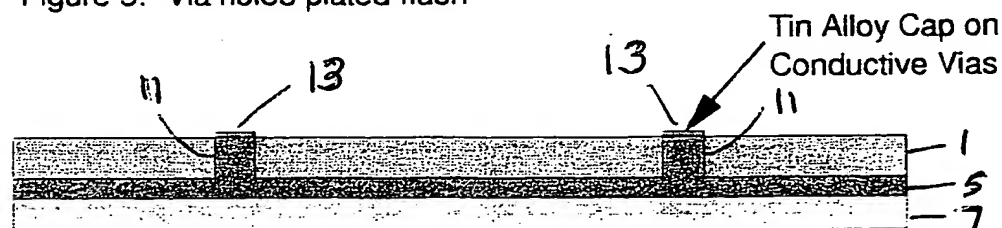


Figure 6. Filled vias overplated with solder alloy

006T60-99E59960

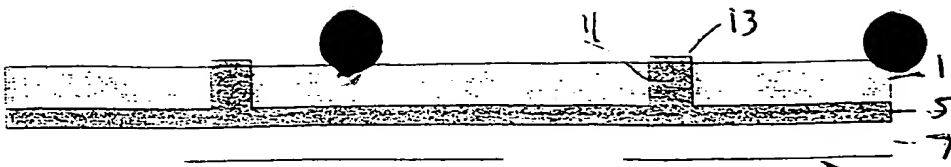


Figure 7. Photo resist applied, exposed and developed

Patterned Photo Resist

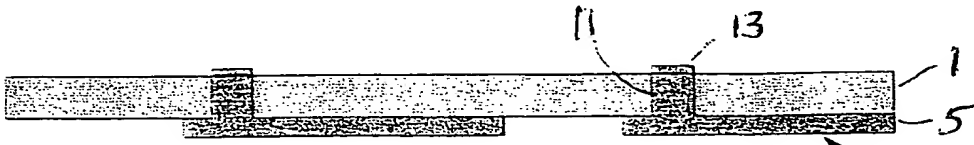


Figure 8. Circuits etched and resist stripped

Etched Circuitry

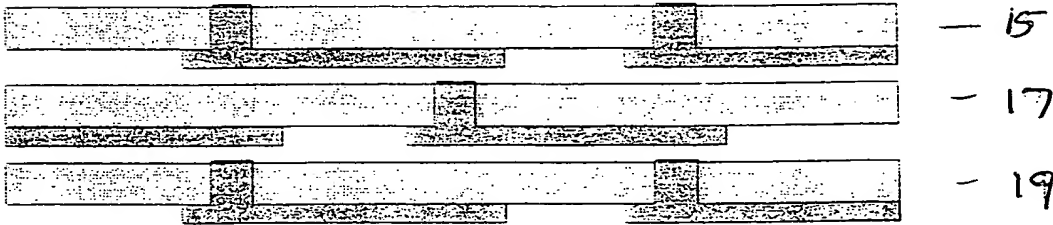


Figure 9. Layers stacked and aligned prior to joining

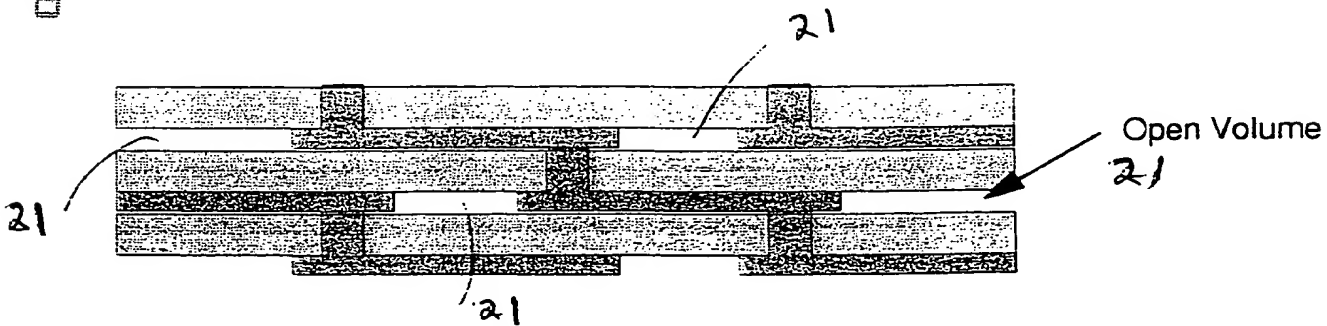


Figure 10. Circuits on adjacent layers joined by soldering

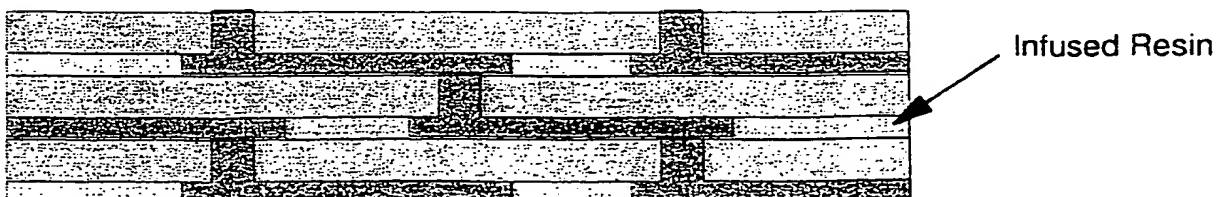


Figure 11. Resin infused and cured to fill and seal open areas

00665355-091900

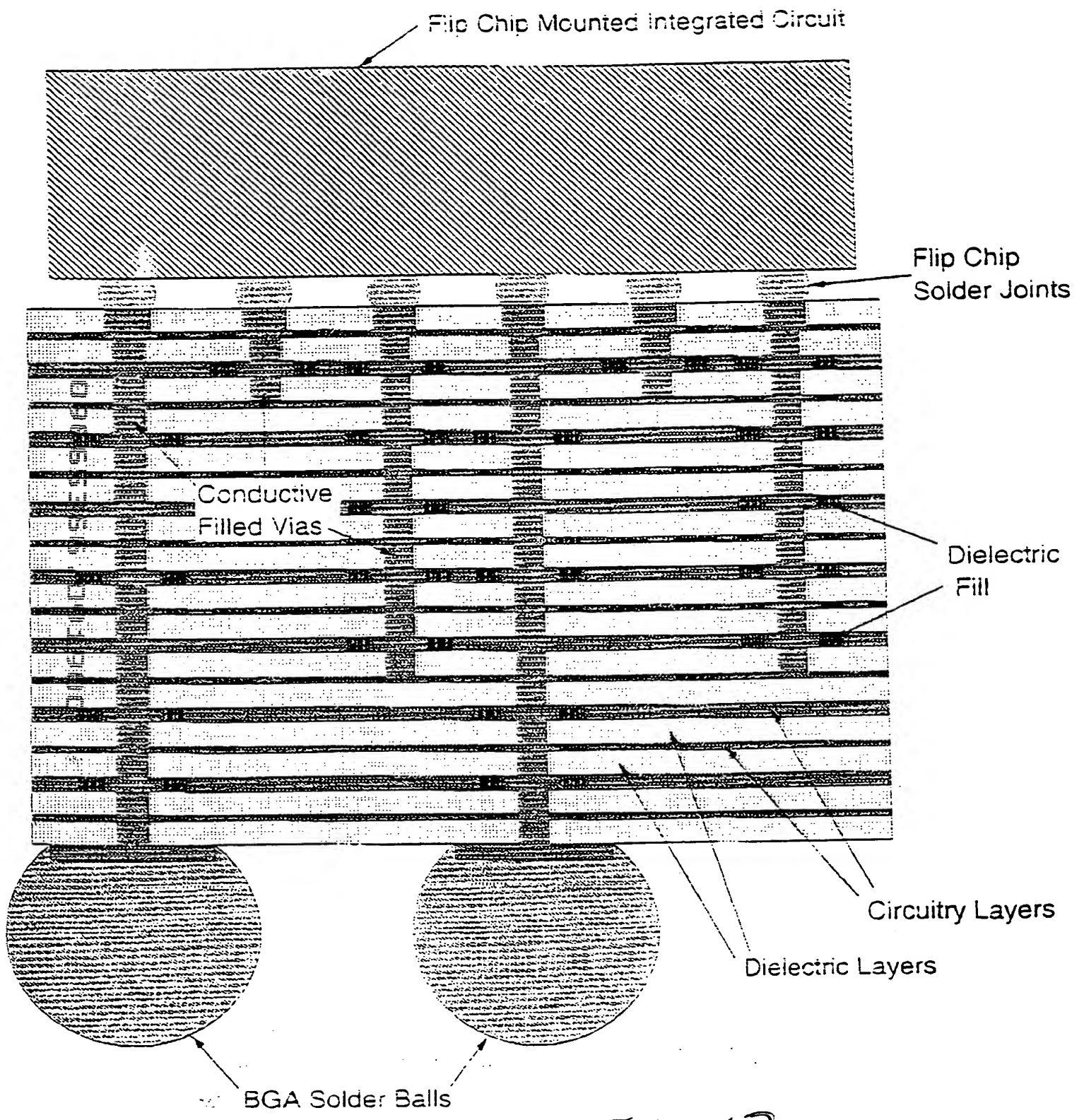


Fig. 12